

C1812X621KATACTU

Aliases (C1812X621KATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 620 pF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

620 pF

1 MHz 1.0Vrms

Time is 1000 Hours

100 GOhms

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

	3.2mm +/-0.3mm	Tolerance	10%
	1mm +/-0.10mm	Voltage DC	250 VDC
	2.3mm MIN	Dielectric Withstanding Voltage	625 VDC
	0.7mm +/-0.35mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
aging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
aging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
aging Quantity	1000	Dissipation Factor	0.1% 1 MHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee

Specifications

Measurement Condition

Insulation Resistance

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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